

<b>FORM PTO-149</b> US DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		App. Docket No. <b>86973RLO</b> Customer No. 01333		Serial No. <del>Not yet assigned</del> <b>10/753,249</b>	
If AFTER the later date of the first Office Action or 3 months from filing, use only with Rule 97(E) Certificate or Fee		Applicant: <b>Kevin P. Klubek, et al.</b>			
<b>LIST OF ART CITED BY APPLICANT</b> <i>(Use several sheets if necessary)</i>		Filing Date <del>herewith</del> <b>8 JAN 2004</b>		Group <del>Not yet assigned</del> <b>1774</b>	

  

U.S. PATENT DOCUMENTS						
Examiner Initial*	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<b>DS</b>	4,769,292	09-06-1988	Tang et al.	—	—	—
<b>DS</b>	5,908,581	06-01-1999	Chen et al.	—	—	—
<b>DS</b>	5,593,788	01-14-1997	Shi et al.	—	—	—
<b>DS</b>	5,141,671	08-25-1992	Bryan et al.	—	—	—
<b>DS</b>	6,582,837	06-24-2003	Toguchi et al.	—	—	—

  

FOREIGN PATENT DOCUMENTS						
Examiner Initial*	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
<b>DS</b>	11-273861	10-08-1999	Japan	—	—	X —
<b>DS</b>	2001-284050	10-12-2001	Japan	—	—	X —
<b>DS</b>	1 162 674 A2	05-28-2001	Europe	—	—	— —

  

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)	
<b>DS</b>	Dresner, RCA Review, 30, <del>332</del> (1969), <b>pg. 322-334.</b>
<b>DS</b>	Tang et al., Applied Physics Letters, 51, <del>913</del> (1987), <b>p. 913-915.</b>
<b>DS</b>	Tang et al., Journal of Applied Physics, 65, <del>3610</del> (1989), <b>pg. 3610-3616.</b>
<b>DS</b>	Popovic et al., Thin Solid Films 2000, 363, 6; SPIE 1998, 3476, <del>68</del> <b>pg. 68-73.</b>
<b>DS</b>	Hamada et al., Applied Phys. Lett. 75, <del>1682</del> (1999), <b>pg. 1682-1684.</b>
<b>DS</b>	U.S. Patent Application Publication 2003/0118866 A1 <b>06/26/2003 Oh et al.</b>

  

EXAMINER <b>Raum Lefanett</b>	DATE CONSIDERED <b>April 27, 2006</b>
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\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.